

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Withdrawn) A circuit device comprising:  
conductive patterns formed on a front surface of a circuit substrate; and  
circuit elements electrically connected respectively to the conductive patterns,  
wherein the conductive patterns include a first conductive pattern and a second  
conductive pattern formed more thickly than the first conductive pattern, and  
front surfaces of the first and second conductive patterns are placed at substantially equal  
levels, and a protruding portion is provided on a back surface of the second conductive pattern,  
the protruding portion protruding, in a thickness direction, from a back surface of the first  
conductive pattern.
  
2. (Currently Amended) A circuit device comprising:  
conductive patterns formed on a front surface of a circuit substrate;  
an insulating layer on the front surface of the circuit substrate; and  
circuit elements electrically connected to the conductive patterns,  
wherein the circuit substrate is metal,  
the insulating layer comprises a resin material,  
the conductive patterns are on the insulating layer and include a first conductive pattern  
and a second conductive pattern formed more thickly thicker than the first conductive pattern,  
and  
back surfaces of the first and second conductive patterns are plaeed at substantially equal  
levels, and a protruding portion is provided on a front surface of the second conductive pattern

and integrally formed with the second conductive pattern in a single body, the protruding portion protruding, in a thickness direction, from a the front surface of the first second conductive pattern,

the circuit elements comprise a power transistor mounted to the front surface of the second conductive pattern, and

an edge portion of the second conductive pattern is formed around the protruding portion, the edge portion having a thickness substantially equal to that of the first conductive pattern and a width larger than the thickness of the first conductive pattern.

3. (Withdrawn) A circuit device comprising:

conductive patterns formed on a front surface of a circuit substrate; and

circuit elements electrically connected to the conductive patterns,

wherein the conductive patterns include a first conductive pattern and a second conductive pattern formed more thickly than the first conductive pattern, and

protruding portions are provided respectively on a front surface and a back surface of the second conductive pattern, the protruding portions protruding in a thickness direction.

4-5. (Canceled)

6. (Withdrawn) The circuit device according to any one of claims 1 and 3, wherein the protruding portion is buried in an insulating layer formed on the front surface of the circuit substrate.

7. (Withdrawn) The circuit device according to any one of claims 1 or 3, wherein the circuit substrate is any one of a metal substrate, a ceramic substrate, a printed board, and a flexible sheet.

8. (Withdrawn) The circuit device according to any one of claims 1 or 3, wherein a first circuit element is connected to the first conductive pattern, and  
a second circuit element having a current-carrying capacitance larger than the first circuit element is connected to the second conductive pattern.

9. (Withdrawn) A method of manufacturing a circuit device, comprising the steps of:  
preparing a conductive foil having a protruding portion provided on a front surface thereof, the protruding portion protruding in a thickness direction;  
bringing the conductive foil into intimate contact with a circuit substrate so as to bury the protruding portion in an insulating layer provided on a front surface of the circuit substrate; and  
forming a first conductive pattern and a second conductive pattern which includes the protruding portion and which is thicker than the first conductive pattern, by partially removing the conductive foil in a region where the protruding portion is not provided.

10. (Withdrawn) A method of manufacturing a circuit device, comprising the steps of:  
preparing a conductive foil having a protruding portion provided on a front surface thereof, the protruding portion protruding in a thickness direction;  
bringing a back surface of the conductive foil into intimate contact with an insulating layer provided on a front surface of a circuit substrate; and  
forming a first conductive pattern and a second conductive pattern which includes the protruding portion and which is thicker than the first conductive pattern, by partially removing the conductive foil in a region where the protruding portion is not provided.

11. (Withdrawn) A method of manufacturing a circuit device, comprising the steps of:  
preparing a conductive foil having protruding portions provided on a front surface and a back surface thereof, the protruding portions protruding in a thickness direction;  
bringing the conductive foil into intimate contact with a circuit substrate so as to bury the protruding portion in an insulating layer provided on a front surface of the circuit substrate; and

forming a first conductive pattern and a second conductive pattern which includes the protruding portions and which is thicker than the first conductive pattern, by partially removing the conductive foil in a region where the protruding portions are not provided.

12. (Withdrawn) The method according to any one of claims 9 to 11, wherein side surfaces of the protruding portion are curved surfaces.

13. (Withdrawn) The method according to any one of claims 9 to 11, wherein the conductive foil is patterned so that an edge portion can remain around the protruding portion, the edge portion having a thickness equal to that of the first conductive pattern.

14. (Withdrawn) The method according to claim 13, wherein a width of the edge portion is made larger than the thickness of the first conductive pattern.

15. (Withdrawn) The method according to any one of claims 9 to 11, wherein the first and second conductive patterns are formed by etching processing.

16. (New) The circuit device according to claim 2, wherein the first conductive pattern is a pattern configured to pass small signals and the second conductive pattern is a pattern configured to pass large signals.

17. (New) The circuit device according to claim 2, wherein the circuit substrate comprises Al or Cu.

18. (New) The circuit device according to claim 2, wherein the insulating layer comprises a filler material.